TWO LAYER OR MULTILAYER PRINTED CIRCUIT BOARD

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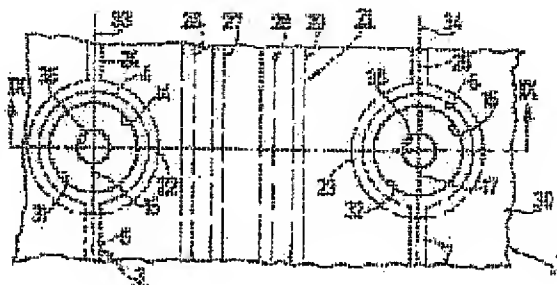**Priority number(s):** AT19910002171 19911031

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Abstract of **JP 5218627 (A)**

PURPOSE: To enable formation of a complete solder junction part between the respective solder parts of first and second conductor patterns by providing equal shapes and areas for first and second solder parts with respect to symmetry lines.
CONSTITUTION: When the plan view of a printed circuit board 1 is observed, a cross-sectional region, which can be divided into two mirror-symmetry regions, having equal shapes and areas with respect to symmetrical lines 33 and 34 to each other, is provided. The centers of holes 31 and 32 of a solder-stopping lacquer layer 30 match with the centers of solder pads 4 and 5 and the centers of judging lands 22 and 23. The radii of holes 31 and 32 of the solder-stopping lacquer layer 30 are made approximately equal to the radii of a bonding agent layer and those of semicircular holes 14 and 15 of the solder lands 22 and 23. In the cross-sectional regions of the holes 31 and 32 of the solder-stopping lacquer layer 30, the bonding agent layer, the cross-sectional regions of the holes 14 and 15 of the solder lands 22 and 23 and a part of the cross-sectional regions of the closed regions of the solder lands 22 and 23 are located. Thus, a complete solder junction part can be formed between the respective solder lands 22 and 23 of first and second conductor patterns 3 and 21.